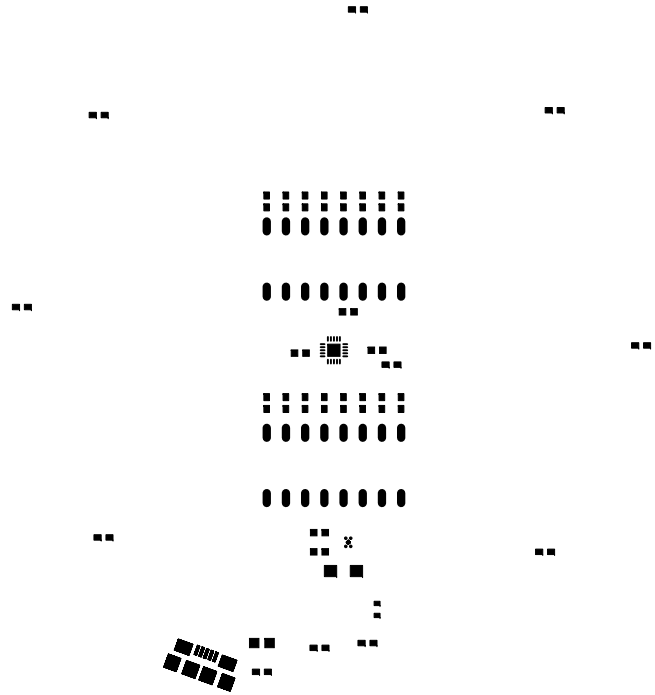


Rapid PCB™

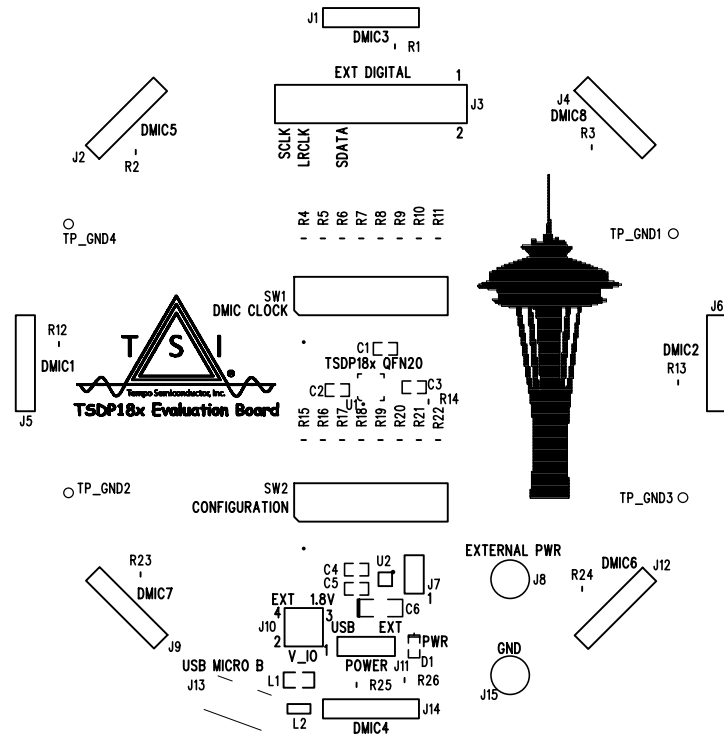
877-887-5777

Artwork for:  
**TEMPO SEMICONDUCTOR, INC.**

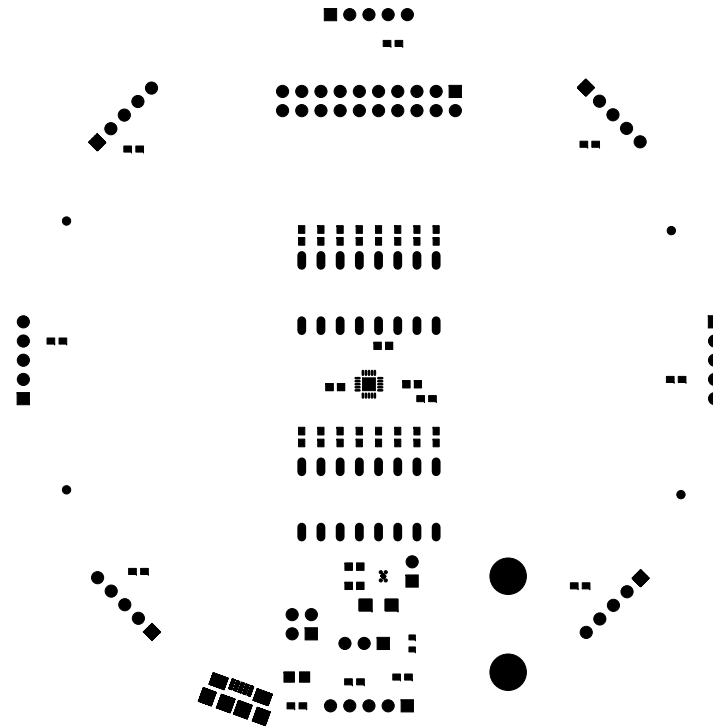
Board Name: SEATTLE EVB		Part Number: REV A
Job No.: TPS.304	Description: TOP SILKSCREEN	Date: 04-05-18



Rapid PCB™  877-887-5777	Artwork for: <b>TEMPO SEMICONDUCTOR, INC.</b>	
	Board Name: SEATTLE EVB	Part Number: REV A
	Job No.: TPS.304	Description: TOP SOLDER PASTE
	Date: 04-05-18	



Rapid PCB™	Artwork for:		TEMPO SEMICONDUCTOR, INC.
	Board Name:		SEATTLE EVB
	Job No.:		TPS.304
	Description:		TOP SILKSCREEN
877-887-5777	Part Number:		REV A
	Date:		04-05-18



Rapid PCB™

877-887-5777

Artwork for:  
TEMPO SEMICONDUCTOR, INC.

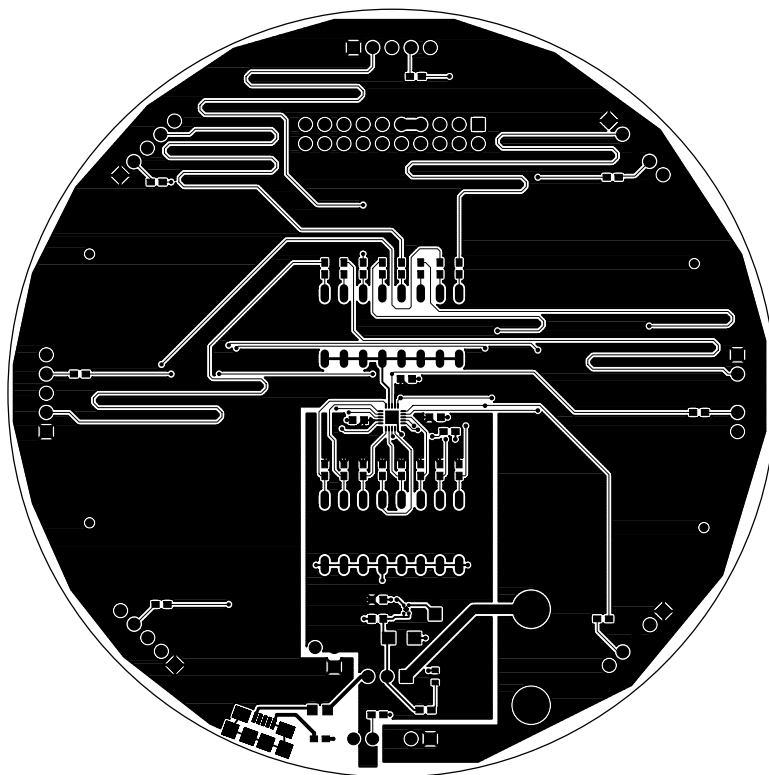
Board Name:  
SEATTLE EVB

Job No.:  
TPS.304

Description:  
TOP SOLDER MASK

Part Number:  
REV A

Date:  
04-05-18



Rapid PCB™

877-887-5777

Artwork for:  
TEMPO SEMICONDUCTOR, INC.

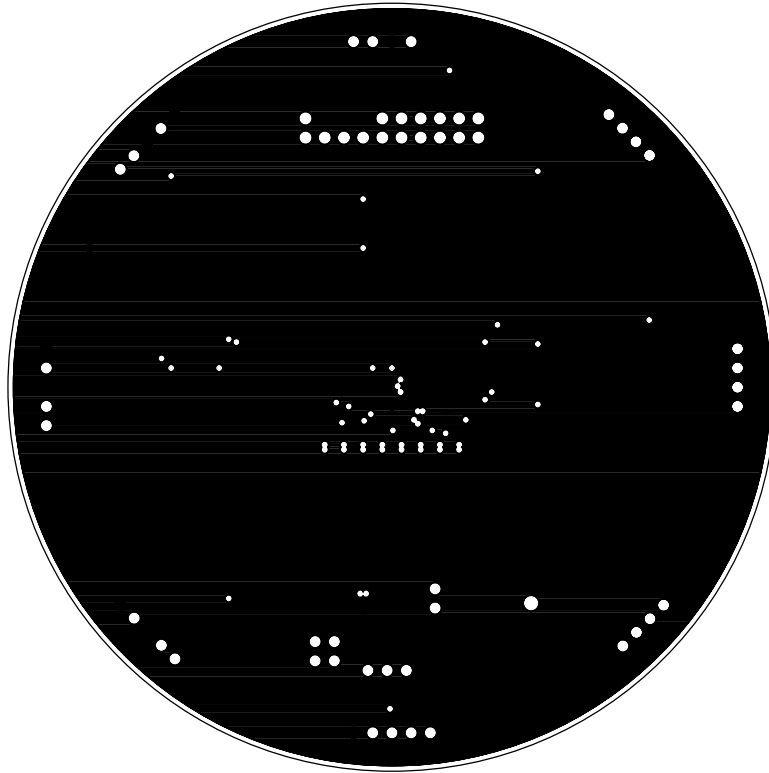
Board Name:  
SEATTLE EVB

Job No.:  
TPS.304

Description:  
COMPONENT SIDE

Part Number:  
REV A

Date:  
04-05-18



Rapid PCB™

877-887-5777

Artwork for:  
TEMPO SEMICONDUCTOR, INC.

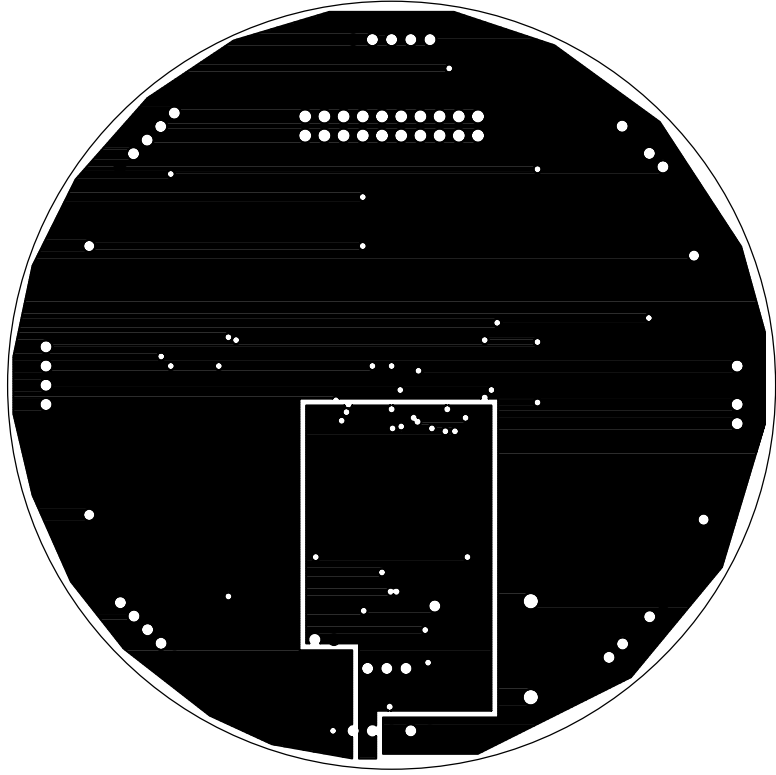
Board Name:  
SEATTLE EVB

Part Number:  
REV A

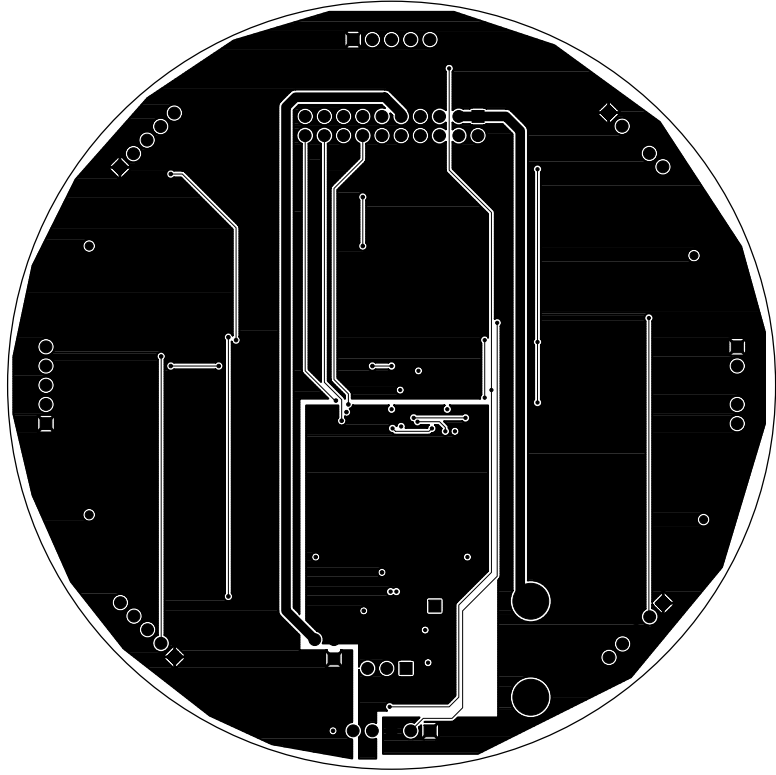
Job No.:  
TPS.304

Description:  
LAYER 2

Date:  
04-05-18



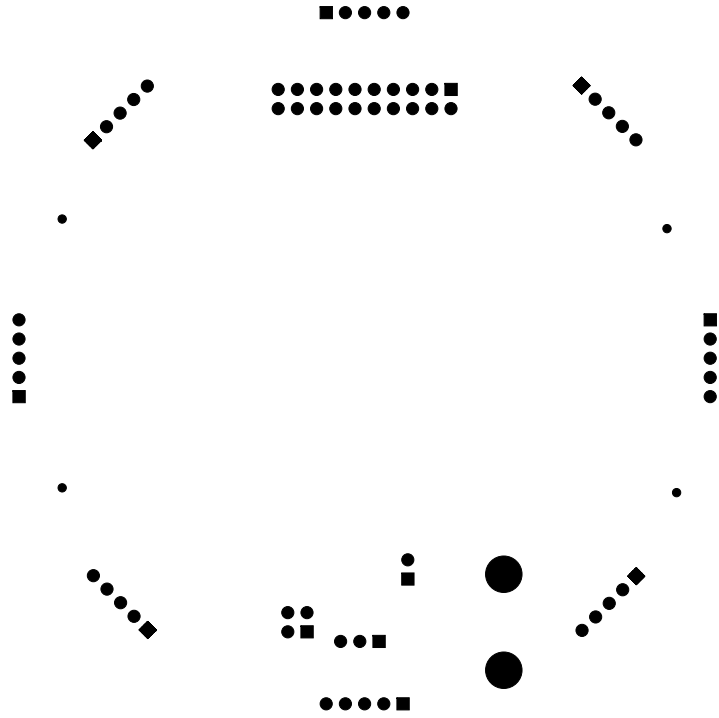
877-887-2777		Job No.: TP2.304	Description: LAYER 3	Date: 04-02-18
Rapid PCB™		SEATTLE EVB		
Board Name: SEATTLE EVB		Part Number: REV A		
Work for: TEMPO SEMICONDUCTOR, INC.		Date: 04-02-18		



877-887-2777		Job No.: TP2.304		Description: SOLDER SIDE		Date: 04-02-18	
Rapid PCB™		Board Name: SEATTLE EVB		Part Number: REV A		Work for: TEMPO SEMICONDUCTOR, INC.	



877-887-2777		Job No.: TP2.304	Description: BOTTOM SOLDER MASK	Date: 04-02-18
Rapid PCB™		SEATTLE EVB		
Board Name: SEATTLE EVB		Part Number: REV A		
Work for: TEMPO SEMICONDUCTOR, INC.				



877-887-2777		Job No.: TP2304	Description: BOTTOM SILKSCREEN	Date: 04-04-18
Rapid PCB™		Board Name: SEATTLE EVB		
		Part Number: REV A		
Tempo SEMICONDUCTOR, INC.		Partwork for:		

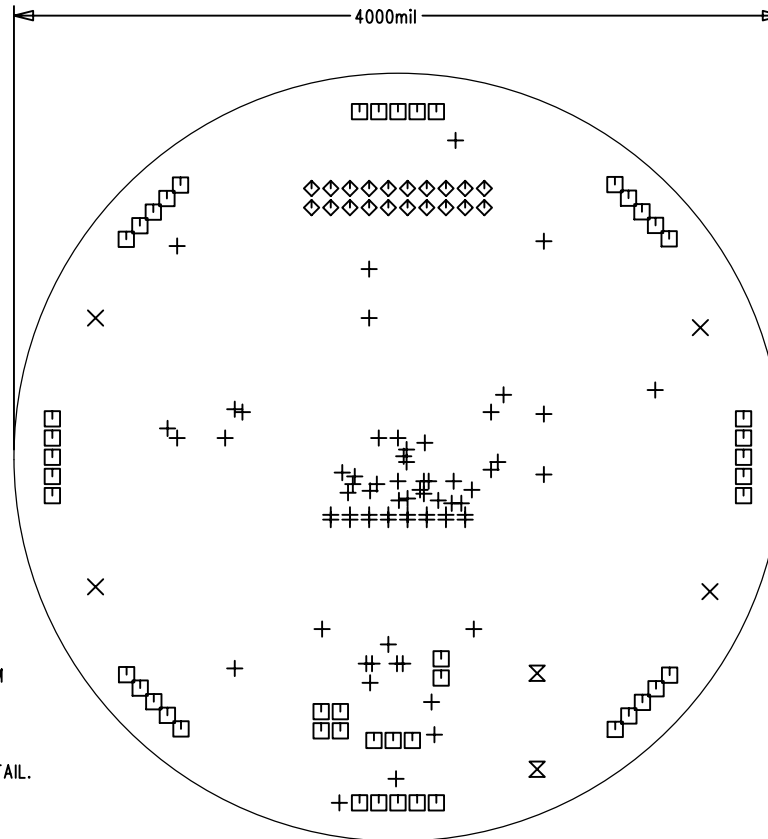
LAYER STACKUP

TOP SILKSCREEN
TOP SOLDER MASK
COMPONENT SIDE
GND PLANE
VCC PLANE
SOLDER SIDE
BOTTOM SOLDER MASK

FILE NAMES

TPSTSS.304
TPSTSM.304
TPSCOMP.304
TPSGND.304
TPSVCC.304
TPSSOLD.304
TPSBSM.304

SCALE: NONE



SIZE	QTY	SYM	PLTD
8	70	+	PLTD
30	4	×	PLTD
35	49	□	PLTD
40	20	◇	PLTD
52	2	⊗	PLTD

NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. MATERIAL SHALL BE COPPER CLAD FR-4 NEMA GRADE PER IPC-4101, COLOR NATURAL.
4. CONSTRUCTION SHALL BE SYMMETRICAL PER LAYER STACKUP DETAIL.
5. COPPER WEIGHT ON INNER LAYERS SHALL BE 1 OZ./SQ. FT..
6. EQUIVALENT COPPER WEIGHT ON OUTER LAYERS SHALL BE 1.0 OZ./SQ. FT BEFORE PLATING.
7. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.0007" COPPER.
8. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE +/- .003".
9. MINIMUM ANNULAR RING SHALL BE 0.001".
10. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
11. PCB THICKNESS SHALL BE 0.062" +/- 0.007".
12. WARP/TWIST SHALL NOT EXCEED .010 INCH PER INCH.
13. FINISH SHALL BE LPI, GREEN SMOBC, BOTH SIDES.  
COPPER SHALL BE PLATED WITH IMMERSION GOLD (ENIG).
14. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.

Rapid PCB™  877-887-5777	Artwork for: <b>TEMPO SEMICONDUCTOR, INC.</b>		
	Board Name: SEATTLE EVB		Part Number: REV A
	Job No.:	Description:	Date:
	TPS.304	DRILL DRAWING	04-05-18

